

P-Channel Enhancement Mode Power MOSFET

Description

The HM4443 uses advanced trench technology to provide excellent $R_{DS(ON)}$, This device is suitable for use as a load switch and battery protection applications.

General Features

• $V_{DS} = -40V, I_{D} = -5.0A$

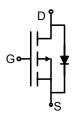
 $R_{DS(ON)}$ < 126m Ω @ V_{GS} =-4.5V

 $R_{DS(ON)}$ < 85m Ω @ V_{GS} =-10V

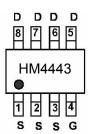
- High power and current handing capability
- Lead free product is acquired
- Surface mount package

Application

- Battery applications
- Load switch



Schematic diagram



Marking and pin assignment



SOP-8 top view

Package Marking and Ordering Information

| Device Marking | Device | Device Package | Reel Size | Tape width | Quantity |
|----------------|--------|----------------|-----------|------------|------------|
| HM4443 | HM4443 | SOP-8 | Ø180mm | 8 mm | 3000 units |

Absolute Maximum Ratings (T_A=25℃unless otherwise noted)

| Parameter | Symbol | Limit | Unit |
|--|------------------|------------|--------------|
| Drain-Source Voltage | V _{DS} | -40 | V |
| Gate-Source Voltage | V _{GS} | ±20 | V |
| Drain Current-Continuous | I _D | -5.0 | Α |
| Drain Current-Pulsed (Note 1) | I _{DM} | -20 | Α |
| Maximum Power Dissipation | P _D | 2.0 | W |
| Operating Junction and Storage Temperature Range | T_{J}, T_{STG} | -55 To 150 | $^{\circ}$ C |

Thermal Characteristic

| Thermal Resistance, Junction-to-Ambient (Note 2) | $R_{\theta JA}$ | 62.5 | °C/W |
|--|-----------------|------|------|
| | 00/1 | | |

Electrical Characteristics (T_A=25 ℃ unless otherwise noted)

| Parameter | Symbol | Condition | Min | Тур | Max | Unit |
|---------------------------------|-------------------|--|-----|-----|-----|------|
| Off Characteristics | | | | | | |
| Drain-Source Breakdown Voltage | BV _{DSS} | V _{GS} =0V I _D =-250μA | -40 | - | - | V |
| Zero Gate Voltage Drain Current | I _{DSS} | V _{DS} =-40V,V _{GS} =0V | - | - | -1 | μΑ |



| Parameter | Symbol | Condition | Min | Тур | Max | Unit |
|------------------------------------|---------------------|--|-----|------|------|------|
| Gate-Body Leakage Current | I _{GSS} | V _{GS} =±20V,V _{DS} =0V | - | - | ±100 | nA |
| On Characteristics (Note 3) | | | • | • | | |
| Gate Threshold Voltage | V _{GS(th)} | V _{DS} =V _{GS} ,I _D =-250μA | -1 | -1.5 | -3 | V |
| Danie Course On Otata Basistana | Б | V _{GS} =-10V, I _D =-5A - | | 73 | 85 | mΩ |
| Drain-Source On-State Resistance | $R_{DS(ON)}$ | V _{GS} =-4.5V, I _D =-4A - | | 98 | 126 | mΩ |
| Forward Transconductance | g fs | V _{DS} =-5V,I _D =-4.1A | 10 | - | - | S |
| Dynamic Characteristics (Note4) | • | | • | • | | |
| Input Capacitance | C _{lss} | \/ 00\/\\ 0\/ | - | 650 | - | PF |
| Output Capacitance | C _{oss} | V_{DS} =-20V, V_{GS} =0V, F=1.0MHz | - | 90 | - | PF |
| Reverse Transfer Capacitance | C _{rss} | F=1.UIVID2 | - | 70 | - | PF |
| Switching Characteristics (Note 4) | | | | • | | |
| Turn-on Delay Time | t _{d(on)} | | - | 9 | - | nS |
| Turn-on Rise Time | t _r | V_{DD} =-20 V , R_L =2 Ω | - | 8 | - | nS |
| Turn-Off Delay Time | t _{d(off)} | V_{GS} =-10V, R_{GEN} =3 Ω | - | 28 | - | nS |
| Turn-Off Fall Time | t _f | | - | 10 | - | nS |
| Total Gate Charge | Qg | \/ - 20\/ - 2.14 | - | 14 | - | nC |
| Gate-Source Charge | Q _{gs} | V_{DS} =-20V, I_{D} =-3.1A, V_{GS} =-10V | - | 2.9 | - | nC |
| Gate-Drain Charge | Q_{gd} | v _{GS} 10v | - | 3.8 | - | nC |
| Drain-Source Diode Characteristics | • | | | • | | |
| Diode Forward Voltage (Note 3) | V _{SD} | V _{GS} =0V,I _S =-2.5A | - | 8.0 | 1.2 | V |
| Diode Forward Current (Note 2) | Is | | - | - | -5.3 | Α |

Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- 3. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.
- 4. Guaranteed by design, not subject to production



Typical Electrical and Thermal Characteristics

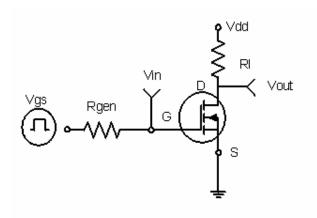


Figure 1:Switching Test Circuit

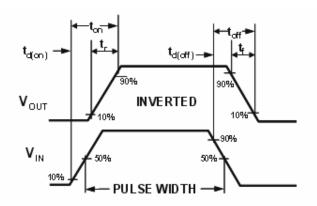
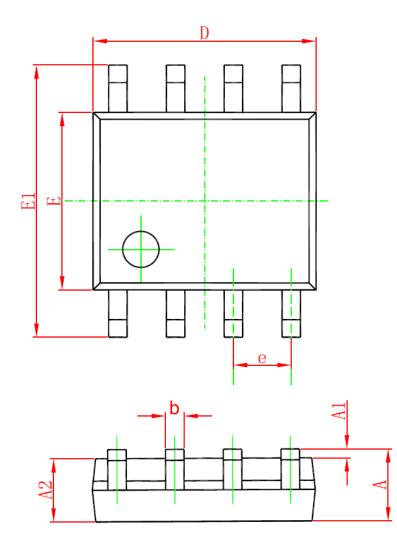
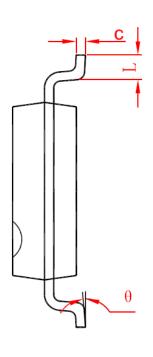


Figure 2:Switching Waveforms



SOP8 PACKAGE OUTLINE DIMENSIONS





| Cl | Dimensions Ir | n Millimeters | Dimensions In Inches | | |
|--------|---------------|---------------|----------------------|--------|--|
| Symbol | Min | Max | Min | Max | |
| А | 1. 350 | 1. 750 | 0. 053 | 0.069 | |
| A1 | 0. 100 | 0. 250 | 0. 004 | 0. 010 | |
| A2 | 1. 350 | 1. 550 | 0. 053 | 0. 061 | |
| b | 0. 330 | 0. 510 | 0. 013 | 0. 020 | |
| С | 0. 170 | 0. 250 | 0. 006 | 0. 010 | |
| D | 4. 700 | 5. 100 | 0. 185 | 0. 200 | |
| Е | 3.800 | 4. 000 | 0. 150 | 0. 157 | |
| E1 | 5. 800 | 6. 200 | 0. 228 | 0. 244 | |
| е | 1. 270 (BSC) | | 0. 050 (BSC) | | |
| L | 0. 400 | 1. 270 | 0. 016 | 0.050 | |
| θ | 0° | 8° | 0° | 8° | |

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